Arrangement Configured to Support Substrate during Dicing Process, and Apparatus and Method for Cutting Tapeless Substrate Using the Arrangement

ABSTRACT OF THE DISCLOSURE

An arrangement configured to support a substrate (102) during a dicing process includes a nest (502) having a first nest side and a second nest side. The nest includes a grid which defines at least one nest opening (504). The nest opening has an opening area that is smaller than an area of a die diced from the substrate. The arrangement further includes a vacuum retainer plate (520) having thereon at least one vacuum pedestal (522). The vacuum pedestal has an upper surface formed of a resilient material and is configured to be disposed through the nest opening when the nest is mated with the vacuum retainer plate (520) to support the substrate on the upper surface.

( Figure 9 )

*G00002*

*162162*